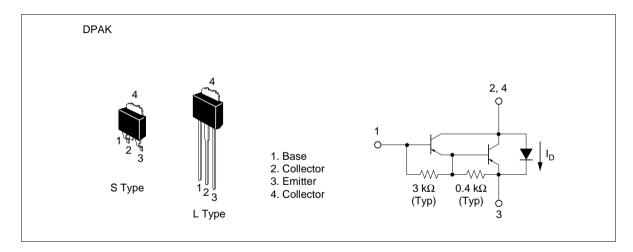
Silicon PNP Triple Diffused

# HITACHI

#### Application

Medium speed power amplifier

#### Outline





#### **Absolute Maximum Ratings** (Ta = 25°C)

Symbol	Rating	Unit V	
V <sub>CBO</sub>	-100		
V <sub>CEO</sub> -80		V	
V <sub>EBO</sub>	-7	V	
Ι <sub>c</sub>	-4	А	
۱ <sub>D</sub> *1	4	А	
I <sub>C(peak)</sub>	-8	А	
Pc*1	20	W	
Tj	150	°C	
Tstg	-55 to +150	°C	
	$     \begin{array}{c}       V_{CBO} \\       V_{CEO} \\       V_{EBO} \\       I_{C} \\       I_{D}^{*1} \\       I_{C(peak)} \\       P_{C}^{*1} \\       Tj     \end{array} $	$V_{CBO}$ -100 $V_{CEO}$ -80 $V_{EBO}$ -7 $I_C$ -4 $I_D^{*1}$ 4 $I_{C(peak)}$ -8 $P_C^{*1}$ 20         Tj       150	

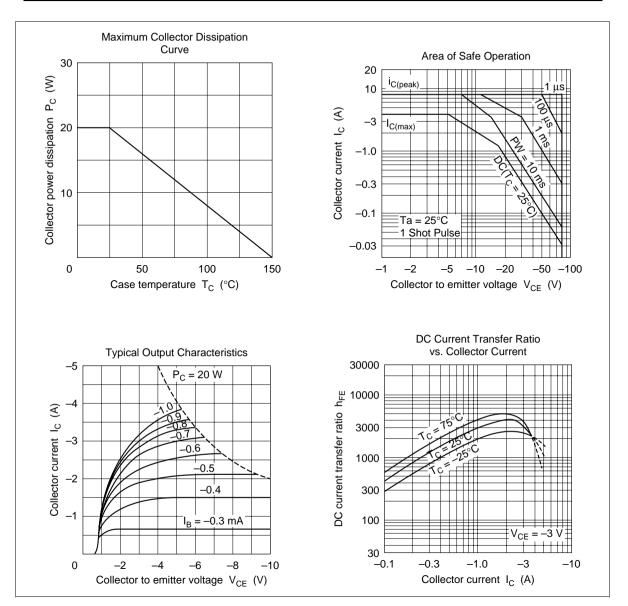
Note: 1. Value at  $T_c = 25^{\circ}C$ 

#### **Electrical Characteristics** (Ta = 25°C)

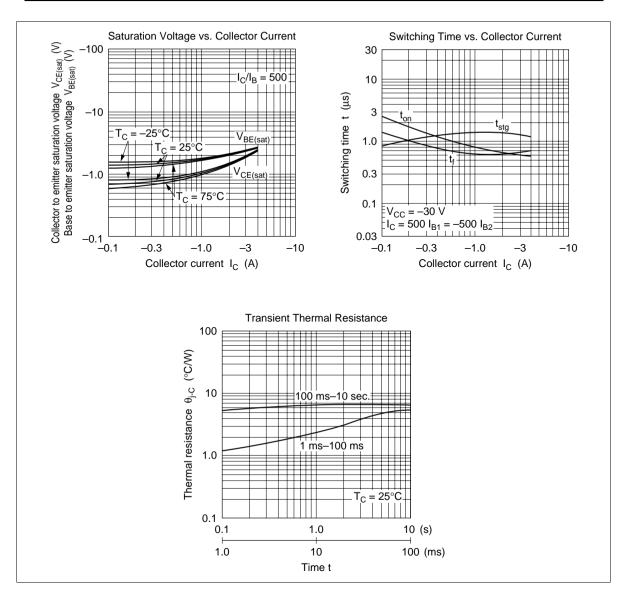
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	-80	-	_	V	$I_{c}$ = -25 mA, $R_{BE}$ = $\infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-7	_	_	V	$I_{\rm E} = -50$ mA, $I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	—	-100	μA	$V_{CB} = -80 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	—	—	-10	μA	$V_{ce}$ = -60 V, $R_{be}$ = $\infty$
DC current transfer ratio	h <sub>FE</sub>	1000	—	20000		$V_{ce} = -3 V, I_c = -2 A^{*1}$
Collector to emitter saturation	$V_{\text{CE(sat)1}}$	—	—	-1.5	V	$I_{\rm C} = -2$ A, $I_{\rm B} = -4$ mA <sup>*1</sup>
voltage	$V_{CE(sat)2}$	—	—	-3.0	V	$I_{\rm C} = -4$ A, $I_{\rm B} = -40$ mA <sup>*1</sup>
Base to emitter saturation	$V_{BE(sat)1}$		_	-2.0	V	$I_{\rm c} = -2$ A, $I_{\rm B} = -4$ mA <sup>*1</sup>
voltage	$V_{BE(sat)^2}$	—	—	-3.5	V	$I_{\rm C} = -4$ A, $I_{\rm B} = -40$ mA <sup>*1</sup>
C to E diode forward voltage	V <sub>D</sub>	_	—	3.0	V	$I_{\rm D} = 4 \ {\rm A}^{*1}$
Turn on time	t <sub>on</sub>	—	0.5	—	μs	$I_{\rm c} = -2$ A, $I_{\rm B1} = -I_{\rm B2} = -4$ mA
Storage time	t <sub>stg</sub>	_	1.5	—	μs	_
Fall time	t <sub>f</sub>		1.0	—	μs	_

Note: 1. Pulse test.

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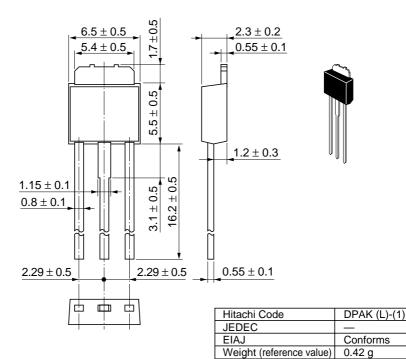


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Unit: mm



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